

Special Issue

Structural Health Monitoring: Latest Applications and Data Analysis

Message from the Guest Editors

Dear Colleagues, This Special Issue is devoted to Structural Health Monitoring (SHM), more precisely to its most recent applications and obtained data analysis. Monitoring the state of engineering structures is unquestionably a timely topic, but it is also a very broad and interdisciplinary one. Both novel sensor systems and measurement, data collecting, and processing techniques are of relevance in this context. SHM techniques encompass all commonly used technical diagnostics and non-destructive testing methods, including electromagnetic, high-frequency, thermovision, radiography, ultrasound, and others. Each of the aforementioned methods presents unique issues, not just in terms of measurement methodology, but data processing as well. As a result, the processing of signals or images for the needs of qualitative and quantitative assessment of the structures under examination is also particularly intriguing in this context. We invite scientists working in the broad field of technical diagnostics and nondestructive testing to submit original work on any of the above-mentioned themes.

Guest Editors

Prof. Dr. Grzegorz Psuj

Center for Electromagnetic Fields Engineering and High-Frequency Techniques, Faculty of Electrical Engineering, West Pomeranian University of Technology in Szczecin, 70-313 Szczecin, Poland

Dr. Barbara Grochowalska (Szymanik)

Center for Electromagnetic Fields Engineering and High-Frequency Techniques, Faculty of Electrical Engineering, West Pomeranian University of Technology in Szczecin, 70-313 Szczecin, Poland

Deadline for manuscript submissions

closed (30 April 2023)



Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



mdpi.com/si/119085

Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
applsci@mdpi.com

mdpi.com/journal/

[applsci](https://mdpi.com/journal/applsci)





Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



[mdpi.com/journal/
applsci](https://mdpi.com/journal/applsci)



About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPlus / SciFinder, and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)